Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	148108	hydrogen adj2 peroxide or "h.sub. 2o.sub.2" or "h.sub.2 o.sub.2" or "h2o2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB		ON	2004/12/02 16:21
S2	351437	sulfuric adj2 acid or "h.sub.2so.sub. 4" or "h.sub.2 so.sub.4" or "h2so4"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:21
S3	194321	(hydro\$1fluoric adj2 acid) or (hydrogen adj2 fluoride) or "hf"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:46
S4	67652	silicide or disilicide or tisi or "tisi"". sub.\$2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 12:43
S5	5289999	etch\$4 or remov\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:48
S6	5844178	S5 or clean\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:38
S7	1019	S1 with S2 with S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:51
S8	14663	S6 with S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:51

			,			
59	87	S7 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:52
S10	2272079	ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:53
S11	219	S1 same S2 same S3 same S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:53
S12	11	S11 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 11:53
S13	13032	S1 with S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 12:16
S14	796	S8 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 12:16
S15	451	S14 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 12:17
S16	67653	silicide or di\$1silicide or tisi or "tisi"".sub.\$2" or mono\$silicide or polysicide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:50

			,			Y
S17	194345	hydrogen adj2 fluoric or S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2004/12/02 13:08
S18	1087	S16 with wet with S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 13:05
S19	2006	S1 same S2 same S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 12:47
S20	20	S18 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	ON	2004/12/02 12:47
S21	195074	dhf or S17	IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:48
S22	14674	S6 with S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 13:12
S23	947	ratio with S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 13:14
S24	46	S21 and S22 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 13:14

S25	1059	(438/745 or 438/755).ccls.	US-PGPUB;	OR	ON	2004/12/03 10:47
			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S26	67653	silicide or di\$1silicide or tisi or "tisi"".sub.\$2" or mono\$silicide or polysicide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:19
S27	31685	etch\$4 adj3 stop\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:42
S28	684	S26 with S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:20
S29	148108	hydrogen adj2 peroxide or "h.sub. 2o.sub.2" or "h.sub.2 o.sub.2" or "h2o2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:21
S30	351437	sulfuric adj2 acid or "h.sub.2so.sub. 4" or "h.sub.2 so.sub.4" or "h2so4"	DERWENT;		ON	2004/12/02 16:21
S31	194321	(hydro\$1fluoric adj2 acid) or (hydrogen adj2 fluoride) or "hf"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:22
S32	194345	hydrogen adj2 fluoric or S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:22

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S33	195074	dhf or S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:23
S34	24	S28 and S29 and S30 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:38
S35	3	S25 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:42
S36	160109	poly\$1si or poly\$1silicon or polycrystal\$5 adj2 (si or silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:42
S37	579019	mask\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:43
S38	26077	S36 with S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 16:44
S39	5839333	opening or hole or aperture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:45
S40	6398	S38 same S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB		ON	2004/12/02 16:45

CAA		C40 1 C20	110 000:15	65		2004/42/02 47 22
S41	52	S40 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/02 17:20
S42	147			OR	ON	2004/12/02 17:20
			EPO; JPO; DERWENT; IBM_TDB			
S43	194321	(hydro\$1fluoric adj2 acid) or (hydrogen adj2 fluoride) or "hf"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:48
S44	194345	hydrogen adj2 fluoric or S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2004/12/03 09:48
S45	195074	dhf or S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:48
S46	259206	ppm	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:49
S47	1304	S45 near15 S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:49
S48	67653	silicide or di\$1silicide or tisi or "tisi. sub.2" or mono\$silicide or polysicide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 09:51

S49	72	S47 and S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:37
S50	2942	(438/654 or 438/655 or 438/664 or 438/671 or 438/683 or 438/751). ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:37
S51	5289999	etch\$4 or remov\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:38
S52	5844178	S51 or clean\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:38
S53	160109	poly\$1si or poly\$1silicon or polycrystal\$5 adj2 (si or silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:42
S54	4038141	heat\$4 or anneal\$4 or thermal\$3 adj3 treat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:45
S55	5839333	opening or hole or aperture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:46
S56	3003	S53 with S54 with S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR-	ON	2004/12/03 10:46
S57	3958	(438/745 or 438/755).ccls. or S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:48

S58	204	S55 and S56 and S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:52
S59	198	S58 and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 10:53